

Semiconductor Bonding Equipment Market Opportunity, Growth Drivers, Industry Trend Analysis, and Forecast 2024 – 2032

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Abstracts

The Global Semiconductor Bonding Equipment Market was valued at USD 530.4 million in 2023 and is projected to indicate a CAGR of 10% from 2024 to 2032. The semiconductor industry is witnessing robust growth, spurred by rising chip demands across sectors like consumer electronics, automotive, telecommunications, and industrial applications. This demand surge is largely driven by technologies such as artificial intelligence (AI), 5G, electric vehicles (EVs), and the Internet of Things (IoT), all of which rely on advanced semiconductor components. This upward trend is set to further bolster the semiconductor industry. For example, in February 2024, the Semiconductor Industry Association projected the semiconductor market would reach USD 1 trillion by 2030. The overall semiconductor bonding equipment industry is classified based on bonding type, equipment type, application, end-use, and region. The market segments based on equipment type include die-bonding equipment, wire-bonding equipment, wafer-bonding equipment, and flip-chip bonding equipment. In 2023, wire bonding equipment dominated the market, capturing over 39% of the revenue share. The wire bonding equipment segment led the market due to its entrenched position in semiconductor packaging. Wire bonding, a time-tested technology, is widely employed in integrated circuit assembly, prized for its reliability and cost-efficiency.

Its versatility in handling diverse semiconductor devices and adaptability to various packaging types further cement its market leadership. The market, segmented by bonding type, includes permanent bonding, temporary bonding, and hybrid bonding. Notably, hybrid bonding is emerging as the fastest-growing segment, projected to expand at a CAGR exceeding 12% during the forecast period. The surge in hybrid bonding equipment can be attributed to its capability of amalgamating multiple bonding technologies, thereby boosting semiconductor packaging performance and flexibility.

This approach facilitates the integration of diverse materials and processes, catering to the stringent demands of advanced applications. In 2023, the Asia Pacific region commanded a dominant share of over 55%, with expectations to maintain this lead throughout the forecast period. The Asia Pacific's supremacy is largely due to its leadership in semiconductor manufacturing and electronics production. Nations such as China, South Korea, Taiwan, and Japan host prominent semiconductor foundries and electronics powerhouses, driving a robust demand for advanced bonding equipment. Coupled with a strong industrial foundation and a concentration of semiconductor manufacturing facilities, the Asia Pacific's status as a global electronic device production hub cements its pivotal role in the semiconductor bonding equipment market.

Contents

Report Content

CHAPTER 1 SCOPE & METHODOLOGY

- 1.1 Market scope & definition
- 1.2 Base estimates & calculations
- 1.3 Forecast parameters
- 1.4 Data sources
 - 1.4.1 Primary
 - 1.4.2 Secondary
 - 1.4.2.1 Paid sources
 - 1.4.2.2 Public sources

CHAPTER 2 EXECUTIVE SUMMARY

- 2.1 Industry 360° synopsis, 2021 - 2032

CHAPTER 3 INDUSTRY INSIGHTS

- 3.1 Industry ecosystem analysis
- 3.2 Vendor matrix
- 3.3 Technology & innovation landscape
- 3.4 Patent analysis
- 3.5 Key news and initiatives
- 3.6 Regulatory landscape
- 3.7 Impact forces
 - 3.7.1 Growth drivers
 - 3.7.1.1 Growth in semiconductor industry
 - 3.7.1.2 Advancements in technology
 - 3.7.1.3 Expansion of 5G networks
 - 3.7.1.4 The growing adoption of electric vehicles (EVs)
 - 3.7.1.5 Increased Investment in R&D
 - 3.7.2 Industry pitfalls & challenges
 - 3.7.2.1 High initial costs
 - 3.7.2.2 Supply chain disruptions
- 3.8 Growth potential analysis
- 3.9 Porter's analysis

- 3.9.1 Supplier power
- 3.9.2 Buyer power
- 3.9.3 Threat of new entrants
- 3.9.4 Threat of substitutes
- 3.9.5 Industry rivalry
- 3.10 PESTEL analysis

CHAPTER 4 COMPETITIVE LANDSCAPE, 2023

- 4.1 Company market share analysis
- 4.2 Competitive positioning matrix
- 4.3 Strategic outlook matrix

CHAPTER 5 MARKET ESTIMATES & FORECAST, BY BONDING TYPE, 2021 - 2032 (USD MILLION)

- 5.1 Key trends
- 5.2 Permanent bonding
- 5.3 Temporary bonding
- 5.4 Hybrid bonding

CHAPTER 6 MARKET ESTIMATES & FORECAST, BY EQUIPMENT TYPE, 2021 – 2032 (USD MILLION)

- 6.1 Key trends
- 6.2 Wire bonding equipment
- 6.3 Die bonding equipment
- 6.4 Flip chip Bonding equipment
- 6.5 Wafer bonding equipment

CHAPTER 7 MARKET ESTIMATES & FORECAST, BY APPLICATION, 2021 – 2032 (USD MILLION)

- 7.1 Key trends
- 7.2 Advanced packaging
- 7.3 Power IC and power discrete
- 7.4 Photonic devices
- 7.5 MEMS Sensors and Actuators
- 7.6 Engineered substrates

7.7 CMOS image sensors

7.8 RF devices

7.9 Others

CHAPTER 8 MARKET ESTIMATES & FORECAST, BY END USE INDUSTRY, 2021 – 2032 (USD MILLION)

8.1 Key trends

8.2 Consumer electronics

8.3 Automotive

8.4 Telecommunications

8.5 Healthcare

8.6 Aerospace & defense

8.7 Industrial

8.8 Others

CHAPTER 9 MARKET ESTIMATES & FORECAST, BY REGION, 2021 - 2032 (USD MILLION)

9.1 Key trends

9.2 North America

9.2.1 U.S.

9.2.2 Canada

9.3 Europe

9.3.1 UK

9.3.2 Germany

9.3.3 France

9.3.4 Italy

9.3.5 Spain

9.3.6 Rest of Europe

9.4 Asia Pacific

9.4.1 China

9.4.2 India

9.4.3 Japan

9.4.4 South Korea

9.4.5 ANZ

9.4.6 Rest of Asia Pacific

9.5 Latin America

9.5.1 Brazil

9.5.2 Mexico

9.5.3 Rest of Latin America

9.6 MEA

9.6.1 UAE

9.6.2 Saudi Arabia

9.6.3 South Africa

9.6.4 Rest of MEA

CHAPTER 10 COMPANY PROFILES

10.1 Applied Materials, Inc.

10.2 Applied Microengineering Ltd.

10.3 ASMPT Ltd (ASM Pacific Technology)

10.4 BE Semiconductor Industries NV (Besi)

10.5 Canon Inc.

10.6 DIAS Automation

10.7 Dr. Tresky AG

10.8 EV Group (EVG)

10.9 Fasford Technology Co., Ltd.

10.10 Hesse GmbH

10.11 Kaijo Shibuya Europe GmbH

10.12 Kulicke and Soffa Industries, Inc.

10.13 MRSI Systems

10.14 Mycronic

10.15 Nidec Corporation

10.16 Palomar Technologies

10.17 Panasonic Connect Co., Ltd.

10.18 Shibaura Mechatronics Corp

10.19 SUSS MicroTec SE

10.20 Tokyo Electron Limited

10.21 TORAY ENGINEERING Co.,Ltd

10.22 TPT Wire Bonder GmbH & Co KG

10.23 Ultrasonic Engineering Co., Ltd.

10.24 WestBond, Inc.

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